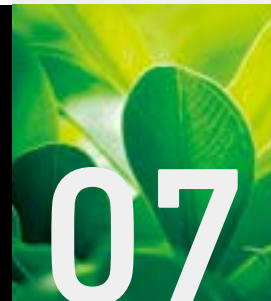


低反り・低弾性の ドライフィルム型封止材料

Low warpage · low modulus dry film type molding material



07

熱硬化型封止フィルム

CELLFIL Series

Thermal-curing type molding film

特長 Features

- **超低反り**
Super-low warpage
- **低熱膨張、低弾性**
Low CTE, Low modulus
- **流動性の異なる2タイプをラインナップ**
Providing two different fluidity types of products
 1. **低流動性/中空封止用: CELLFIL 909S (量産品)**
Low-flow type for hollow molding: CELLFIL 909S (Mass production)
 2. **高流動性/埋め込み封止用: CELLFIL 917XS (開発品)**
High-flow type for filling molding: CELLFIL 917XS (Under development)

特性 Properties

Warpage after cure on thin CCL

Test Coupon	Conventional	CELLFIL
<p>100μm DF</p> <p>200μm CCL</p>		<p>No warping</p>

部品の寸法安定性向上

X-section after molding

CELLFIL 909S	CELLFIL 917XS
<p>CELLFIL</p> <p>Chip</p> <p>拡大</p> <p>中空構造形成可能</p>	<p>表面平滑性良好: Flat surface</p> <p>CELLFIL</p> <p>100μm</p> <p>下地の凹凸の影響無し</p>

Material property	Unit	CELLFIL 909S	CELLFIL 917XS
Tg (TMA)	deg.C	155-165	165-175
CTE α 1	ppm/deg.C	7-10	15-18
Young's modulus	GPa	7-9	6-8

用途 Application

- CELLFIL 909S: SAW Filter, Molding
- CELLFIL 917XS: MIS, ETS, Molding